Title:	DAC3482 Da	ata S	She	et							
Custom	er Contact:	PC	N Ma	anager_	Phon	e: +1(214) 48	0-6	503	7 Dept:	Qu	ality Services
Proposed 1 st Ship Da				Not Estimated Sar		mp	nple Availability: Not Applicable			Not Applicable	
Change											
	embly Site			Assem				Щ	Assembly		
Des								<u> </u>	Mechanical Specification		
	t Site		<u>H</u>			oing/Labeling		\vdash	Test Process		
	fer Bump Site		\mathbb{H}	Wafer Bump Material			H	Wafer Fab Process			
Wafer Fab Site Wafer Fab Materials Wafer Fab Process						ocess					
PCN Details											
Descrip	tion of Chang	je:									
and late chip pha device c	The product datasheet(s) is being updated to change the description in device synchronization and latency specifications in order to reflect accurate operation. Information regarding the onchip phase-locked loop is also updated to describe additional production test coverage and device capabilities. The following change history provides further details. These changes may be reviewed at the										
datasne	et links provide	ea.									

PCN Number:

20130716000

PCN Date: 07/31/2013



ww.ti.com SLAS748E – MARCH 2011 – REVISED JULY 2013

CI	nanges from Revision D (August 2012) to Revision E	Page
•	Changed Power Supply Specification Table under Electrical Specification. This specification depends on the enhanced production test coverage and is specific to devices with certain date code. Refer to Clarifications for DAC3482 Power Supply and Phase-Locked Loop Specification Section for details	12
•	Deleted Note (5) in Power Consumption Specification to reflect the latest DAC3482 speed specification	12
•	Changed DACCLKP/N typical clock swing specification to reflect commonly used LVPECL driver	13
•	Changed DACCLKP/N typical clock swing specification to reflect commonly used LVPECL driver	13
•	Changed DACCLK driver requirement to reflect actual device performance under commonly used LVPECL drivers .	13
•	Changed Analog Output Specification Table under Electrical Specification. This specification depends on the enhanced production test coverage and is specific to devices with certain date code. Refer to Clarifications for DAC3482 Power Supply and Phase-Locked Loop Specification Section for details	16
•	Changed Digital Latency Specification for QMC to reflect the actual DAC3482 parameter	16
•	Changed Digital Latency Specification for Inverse Sinc to reflect the actual DAC3482 parameter	16
•	Added Phase-Locked Loop Specification Table under Electrical Specification. This specification depends on the enhanced production test coverage and is specific to devices with certain date code. Refer to Clarifications for DAC3482 Power Supply and Phase-Locked Loop Specification Section for details	17
	Changed pll_vco(6:0) to pll_vco(5:0) to reflect actual bit width in the register	
	Changed config45, bit12:1 default value to reflect the actual default register value	
	Changed config45, bit0 description to clarify additional DAC3482 behavior	
	Changed syncsel fifoout(3:0) description to clarify the FIFO read pointer reset capture method and limitation	
•	Changed information to SINGLE SYNC SOURCE MODE section to clarify the latency limitation of Single Sync Source Mode	
•	Added "the effect of bypassing the FIFO" in the Bypass Mode section to clarify the operation of FIFO, LVDS FRAME, and LVDS SYNC in FIFO Bypass Mode	53
•	Changed PLL Mode section with additional operating recommendations for the DAC3482 on-chip PLL	55
•	Changed information to MULTI-DEVICE OPERATION: SINGLE SYNC SOURCE MODE section to clarify the latency limitation of Single Sync Source Mode	59
	Changed Figure 64 to clarify the latency limitation of Single Sync Source Mode	60
•	Changed Data Pattern Checker section with additional operating recommendations	69
•	Added additional requirements for Block Parity section when byte wide input data mode is selected	
•	Changed the NCO setting description in the Example Start-up Sequence Section to reflect the example register writes	

Device Family	Change From:	Change To:
DAC3482	SLAS748D	SLAS748E

The updated datasheet(s) can be accessed by the following link(s):

http://www.ti.com/product/dac3482

Reason for Change:					
To accurately reflect device characteristics and device capabilities.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
Electrical specification performance changes as indicated above.					
Changes to product identification resulting from this PCN:					
None					
Product Affected:					
DAC3482IRKD25	DAC3482IRKD25 DAC3482IRKDT				
DAC3482IRKDR	DAC3482IZAY				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com